

Title (en)

OPTICAL ELEMENT, RADIATION-EMITTING COMPONENT AND METHOD FOR PRODUCING AN OPTICAL ELEMENT

Title (de)

OPTISCHES ELEMENT, STRAHLUNGSEMITTERENDES BAUELEMENT UND VERFAHREN ZUR HERSTELLUNG EINES OPTISCHEN ELEMENTS

Title (fr)

ÉLÉMENT OPTIQUE, COMPOSANT ÉMETTEUR DE RAYONNEMENT ET PROCÉDÉ DE RÉALISATION D'UN ÉLÉMENT OPTIQUE

Publication

EP 2067180 A2 20090610 (DE)

Application

EP 07817578 A 20070926

Priority

- DE 2007001736 W 20070926
- DE 102006046301 A 20060929

Abstract (en)

[origin: DE102006046301A1] The optical element (1) has a base body (2), which contains a basic material, and a filling body (3), which contains a filling material (7), where the filling body adheres to the base body. The optical element is provided for the formation of radiation. The basic material contains glass and is different from the filling material, which contains silicon material. The base body has a hollow space, which is filled with filling material, where the form of the filling body is determined by the hollow space. Independent claims are also included for the following: (1) a radiation-emitting component, which has an optical element and a radiation-emitting semiconductor body (2) a method for the production of an optical element involves developing a base body and filling a filling material in the base body.

IPC 8 full level

H01L 33/58 (2010.01); **H01L 33/54** (2010.01)

CPC (source: EP US)

H01L 33/58 (2013.01 - EP US); **H01L 25/0753** (2013.01 - EP US); **H01L 33/54** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US);
H01L 2924/0002 (2013.01 - EP US); **H01L 2933/005** (2013.01 - EP US)

C-Set (source: EP US)

H01L 2224/48091 + **H01L 2924/00014**

Citation (search report)

See references of WO 2008040317A2

Citation (examination)

JP 2002252376 A 20020906 - SEIWA ELECTRIC MFG

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

DE 102006046301 A1 20080403; CN 101553937 A 20091007; CN 101553937 B 20120620; EP 2067180 A2 20090610;
JP 2010505253 A 20100218; KR 101653409 B1 20160909; KR 20090064472 A 20090618; TW 200840091 A 20081001; TW I378572 B 20121201;
US 2010025707 A1 20100204; WO 2008040317 A2 20080410; WO 2008040317 A3 20080605

DOCDB simple family (application)

DE 102006046301 A 20060929; CN 200780035948 A 20070926; DE 2007001736 W 20070926; EP 07817578 A 20070926;
JP 2009529529 A 20070926; KR 20097008753 A 20070926; TW 96136505 A 20070929; US 44264107 A 20070926